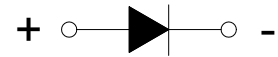
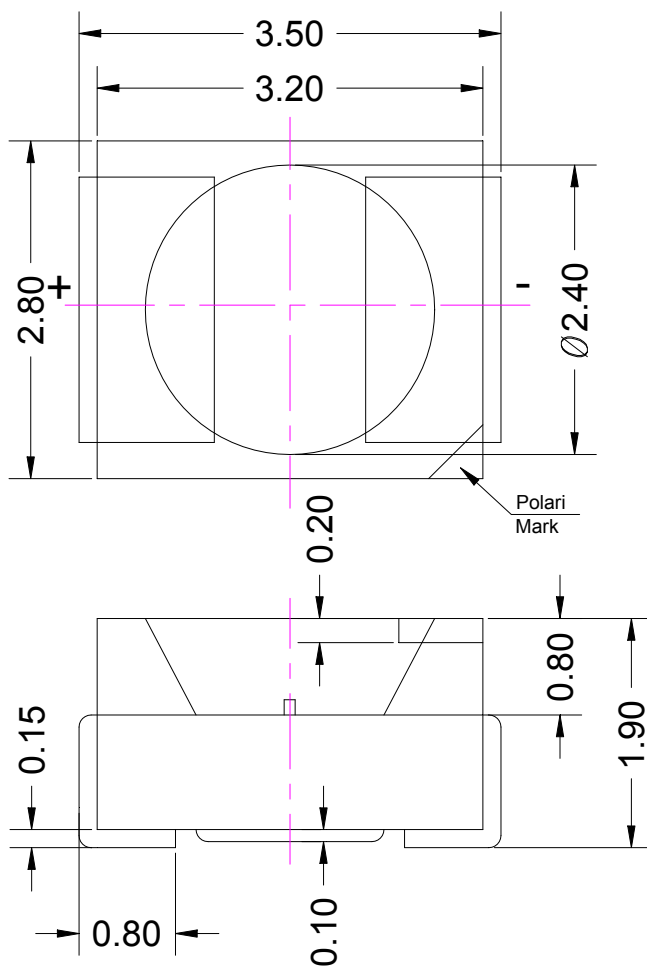




Wen Li	Fang Yang	Jiang Yang	Fang Wang



Tolerance: 0.25(0.01)



Unit mm

Color Pre Green

Lens-color Water clear

Emission Material InGaN

Drawing by Polari a ion



3 Charac eri ic

For ard c rren	If	30				mA
Re er e ol age	Vr	5				V
Po er di ipa ion	Pd	110				mW
Opera ing empera re range	Top	-25 +80				C
S orage empera re range	T g	-30 +80				C
Peak p l ing c rren 1/8 d f=1KH	Ifp	125				mA
Wa eleng h a peak emi ion	If=20mA	peak	515	520	525	nm
Spec ral half band id h	If=20mA			10		
For ard ol age	If=20mA	Vf	3.0		3.6	V
L mino in en i	If=20mA	I	800	1100	1300	mcd



Viewing angle at 50% IV	If=10mA	--	120	--	Deg
Reverse current	Vr=5V	Ir	--	5	A
Useful life	-	IF=20mA	100000		H

Typical Electrical/Optical Characteristic Curve
(Ta=25 Unless Otherwise Noted)

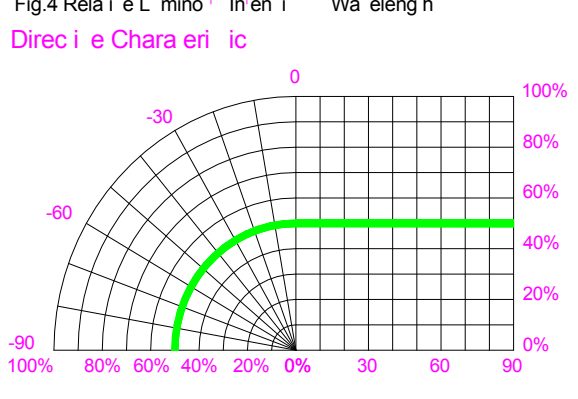
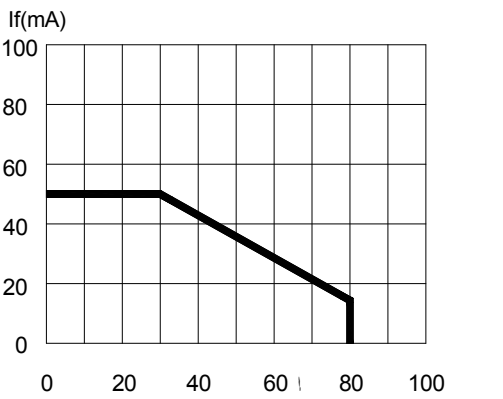
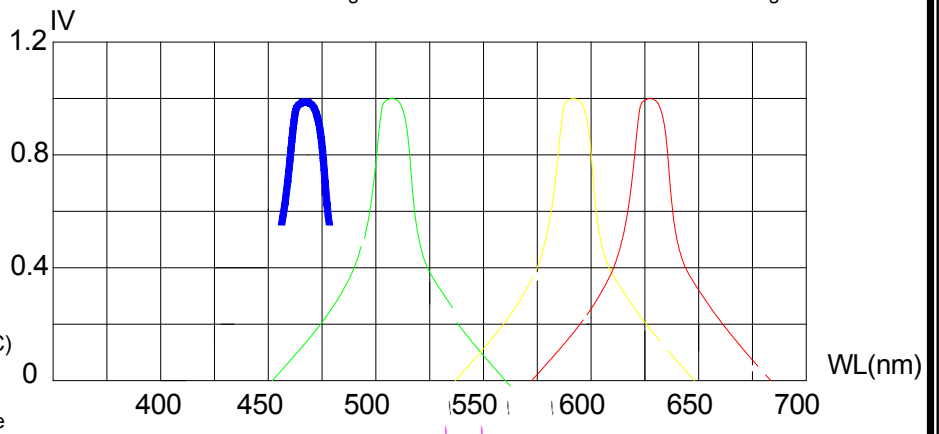
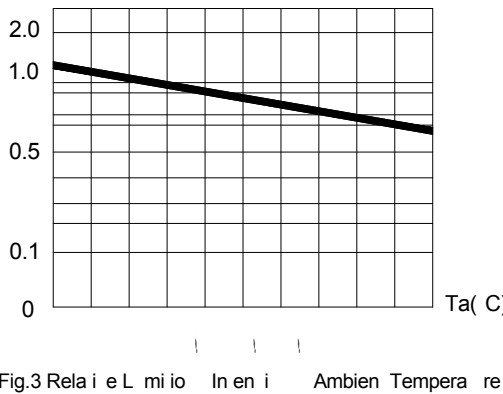
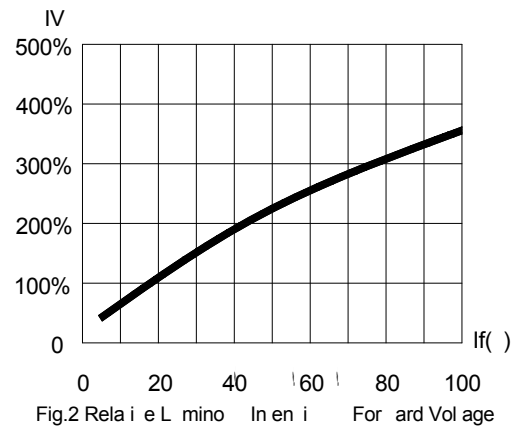
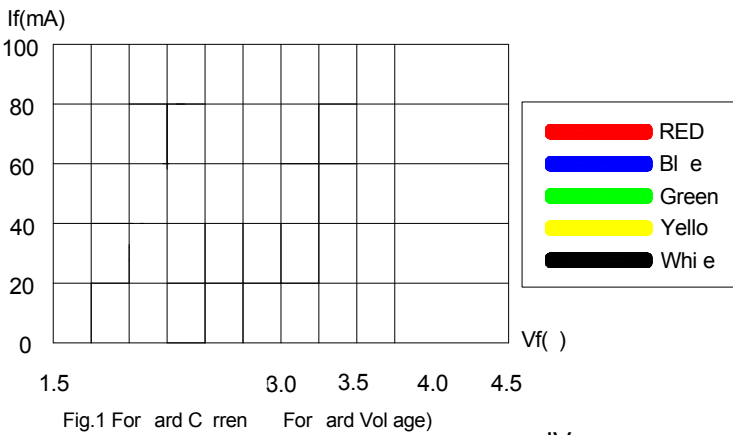


Fig.5 Maximum Forward Current vs Ambient Temperature



1	Tin-plated	Temp 260 ± 5	5 sec.	76 PCS	0/1
2	Back & forth under high & low temp alternately	High temp. +85 30min to 5min to -55 30min	50 bo	76 PCS	0/1
3	Heat shocking	High temp. +100 30min To 10 sec to -10 30min	50 bo	76 PCS	0/1
4	High temp.	Temperature 100	1000 Hr.	76 PCS	0/1
5	Low temp.	-55	1000 Hr.	76 PCS	0/1
6	Life span	VF=1.9V IF=20mA	1000 Hr.	76 PCS	0/1
7	Temperature high temp. & high humidity	85 ± 2/85%RH	1000 Hr.	76 PCS	0/1

i Iron Soldering: The Iron (max 30W) end temperature less than 300 °C, soldering time 3 seconds, soldering position minimum 2mm from body.

ii Dip Soldering: Max temperature is 260 °C, time 5s, the position is minimum 2mm from body.

i Bracket must be bent only if 2mm from colloid.

ii Bracket mold must be finished by fire or professional.

iii Bracket mold must be finished before soldering.

i Bracket mold holder should be connected between the pin, the distance gap of lead and the circuit board.

i. Holder be placed in order of all the device in case of wrong polarity. Device can be overloaded or heat component working condition can replace the limit.

ii. Holder not assemble LED when the lead are deformed.

iii. When decide to assemble in hole, according to the size of hole and hole distance of the line base

i. Suggesting guard heat positioning

i. Holder avoid any kind of shake or force on LED, before the soldering temperature return normal.

Holder be careful. When clean the body with chemical. Some chemical may bring damage to the surface, and bring color fading, such as, Trichloroethylene, Acetone. Should use ethanol or isopropyl alcohol, dip for no more than 3 minutes under the normal temperature.

